



### Features

- Drain-Source Breakdown Voltage  $V_{DSS} - 20\text{ V}$
- Drain-Source On-Resistance
  - $R_{DS(ON)} 42\text{m}\Omega$ , at  $V_{GS} = -4.5\text{V}$ ,  $I_{DS} = -3.8\text{A}$
  - $R_{DS(ON)} 57\text{m}\Omega$ , at  $V_{GS} = -2.5\text{V}$ ,  $I_{DS} = -3.0\text{A}$
- Continuous Drain Current at  $T_C=25^\circ\text{C}$   $I_D = -3.8\text{A}$
- Advanced high cell density Trench Technology
- RoHS Compliance & Halogen Free

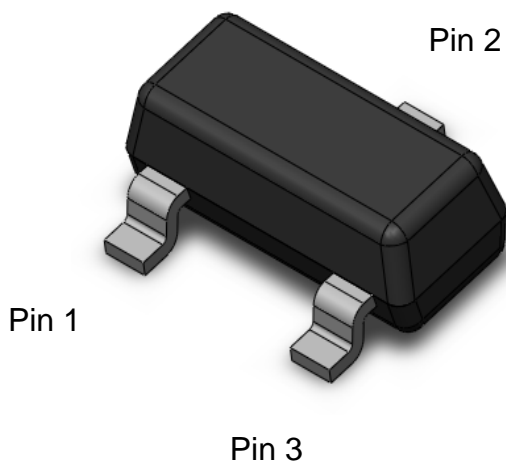
### Applications

- Power Management
- Lithium Ion Battery

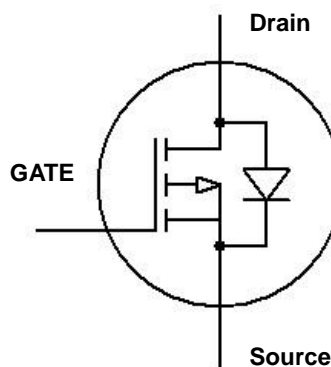
### Description

The CTL0382PS uses high performance Trench Technology to provide excellent  $R_{DS(ON)}$  and low gate charge which is suitable for most of the synchronous buck converter applications .

### Package Outline



### Schematic



**Gate:**      **Pin 1**  
**Drain:**     **Pin2**  
**Source:**    **Pin3**

**Absolute Maximum Rating at 25°C**

<b>Symbol</b>	<b>Parameters</b>	<b>Ratings</b>	<b>Units</b>	<b>Notes</b>
$V_{DS}$	Drain-Source Voltage	-20	V	
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V	
$I_D$	Continuous Drain Current	-3.8	A	1
$I_{DM}$	Pulsed Drain Current	-15	A	1
$P_D$	Total Power Dissipation	1.25	W	2
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$T_J$	Operating Junction Temperature Range	-55 to 150	°C	

**Thermal Characteristics**

<b>Symbol</b>	<b>Parameters</b>	<b>Test Conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Units</b>	<b>Notes</b>
$R_{\theta JA}$	Thermal Resistance Junction-Ambient (t=10s)		-	200	-	°C/W	1,4

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$  (unless otherwise specified)**Static Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$B_{V_{DS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = -250\mu A$	-20	-	-	V	
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS} = -20V, V_{GS} = 0V$	-	-	-1	$\mu A$	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	$\pm 100$	nA	

**On Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS} = -4.5V, I_D = -3.8A$	-	42	55	m $\Omega$	Fig 4
		$V_{GS} = -2.5V, I_D = -3.0A$	-	57	62	m $\Omega$	
$V_{GS(TH)}$	Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu A$	-0.4	-	-1.0	V	Fig 5

**Dynamic Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$C_{ISS}$	Input Capacitance	$V_{DS} = -10V,$ $V_{GS} = 0V,$ $f=1MHz$	-	786	-	pF	Fig 3
$C_{OSS}$	Output Capacitance		-	76	-		
$C_{RSS}$	Reverse Transfer Capacitance		-	90	-		

**Switching Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$T_{D(ON)}$	Turn-On Delay Time	$V_{DS} = -10V, V_{GS} = -4.5V,$ $R_G = 3\Omega, I_D = -3.8A$	-	6.5	-	ns	Fig 11 & 12
$T_R$	Rise Time		-	31	-		
$T_{D(OFF)}$	Turn-Off Delay Time		-	30.5	-		
$T_F$	Fall Time		-	12	-		
$Q_G$	Total Gate Charge	$V_{DS} = -10V, V_{GS} = -4.5V,$ $I_D = -3.8A$	-	8.7	-	nC	Fig 9 & 10
$Q_{GS}$	Gate-Source Charge		-	1.65	-		
$Q_{GD}$	Gate-Drain (Miller) Charge		-	2.5	-		

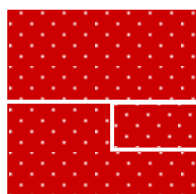


**Drain-Source Diode Characteristics**

<b>Symbol</b>	<b>Parameters</b>	<b>Test Conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Units</b>	<b>Notes</b>
V <sub>DS</sub>	Drain-Source Forward Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = -3.8A			1.2	V	
I <sub>S</sub>	Continuous Forward Current				-3.8	A	1

Note:

- 1. The power dissipation is limited by 150°C junction temperature.
- 2. Device mounted on a glass-epoxy board



FR-4  
25.4 × 25.4 mm .  
2 Oz Copper

Actual Size

- 3. The data tested by pulsed , pulse width ≤ 300μs , duty cycle ≤ 2%
- 4. Thermal Resistance follow JESD51-3.



Typical Characteristic Curves

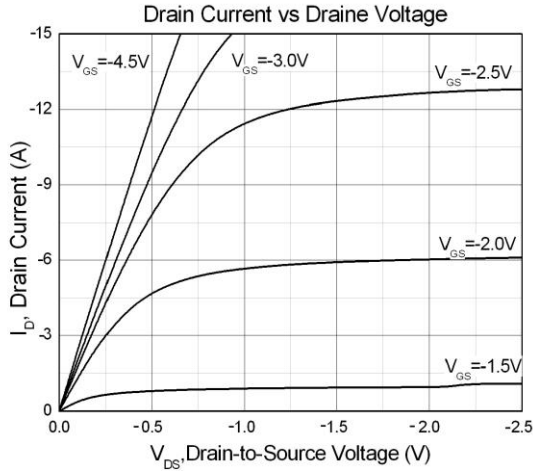


Figure 1

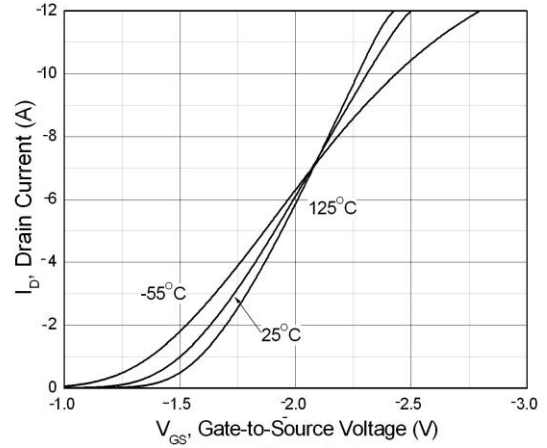


Figure 2

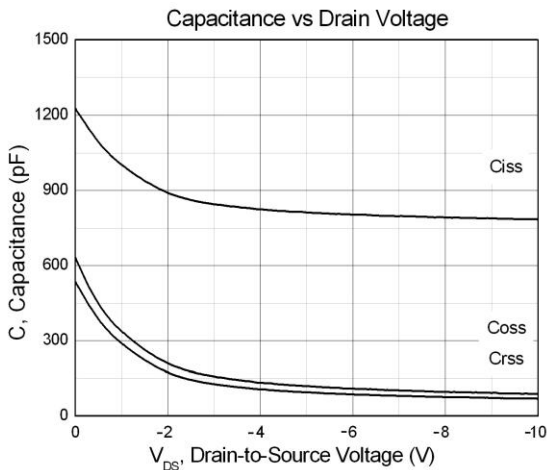


Figure 3

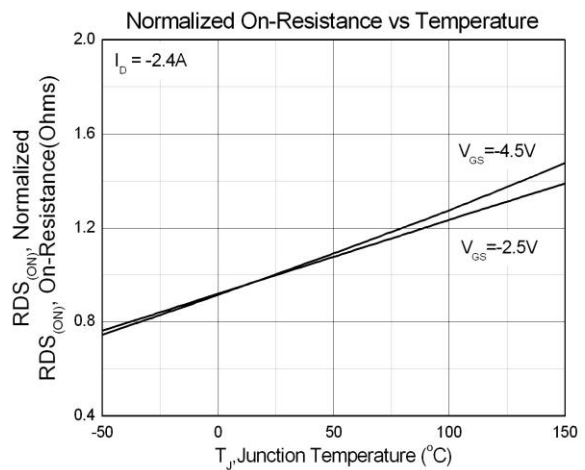


Figure 4

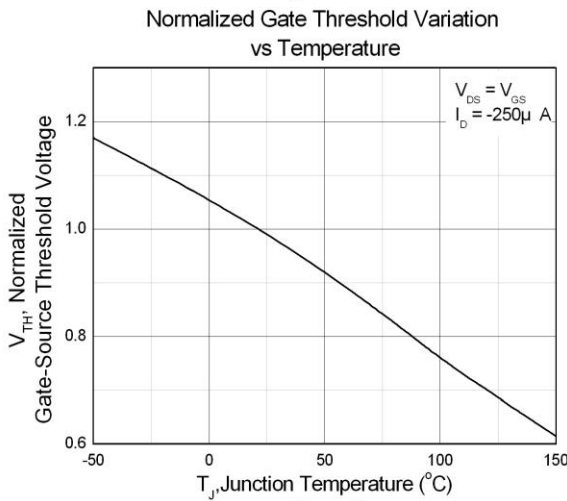


Figure 5

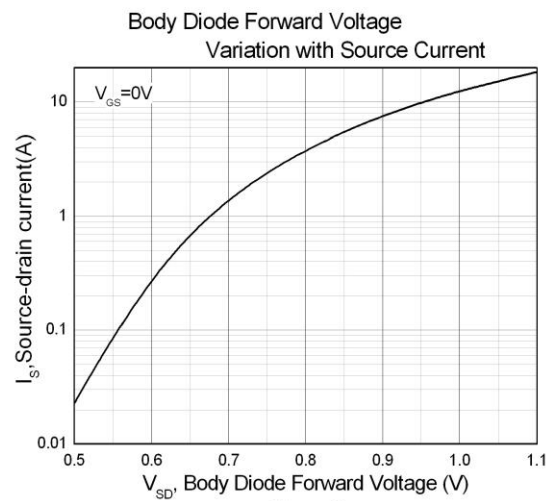
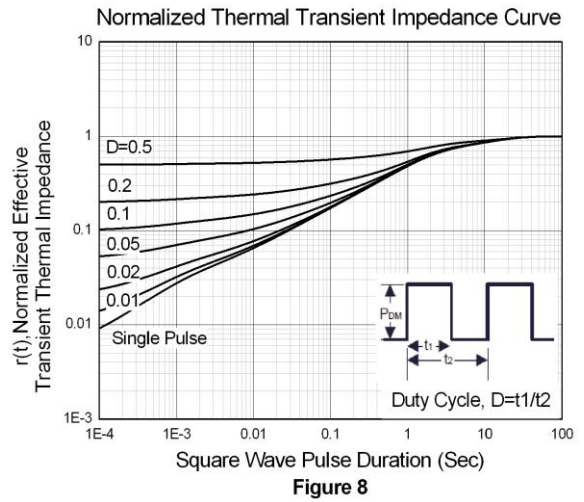
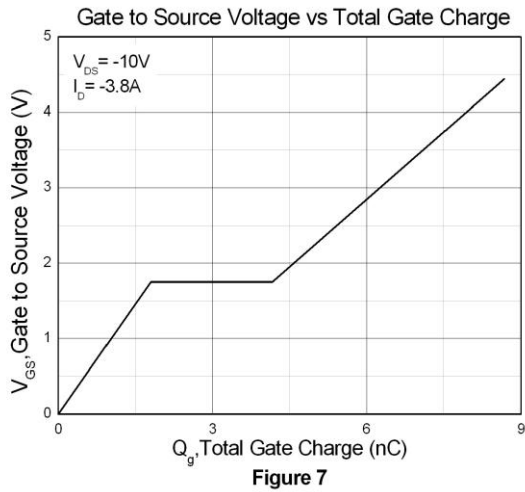


Figure 6





Test Circuits & Waveforms

Figure 9: Gate Charge Test Circuit

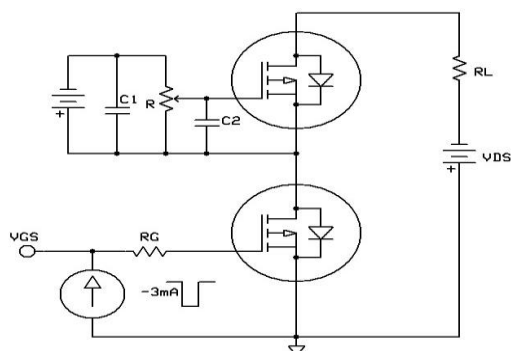


Figure 10: Gate Charge Waveform

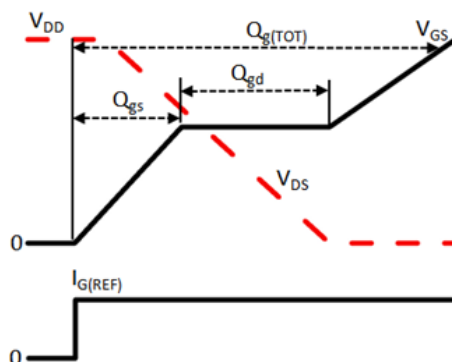


Figure 11: Switching Time Test Circuit

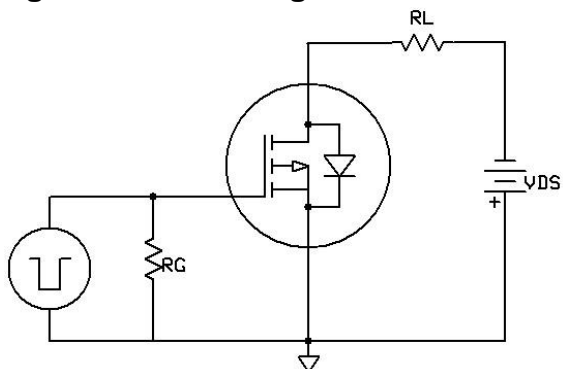
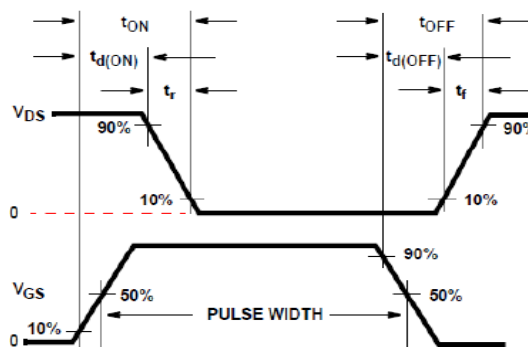
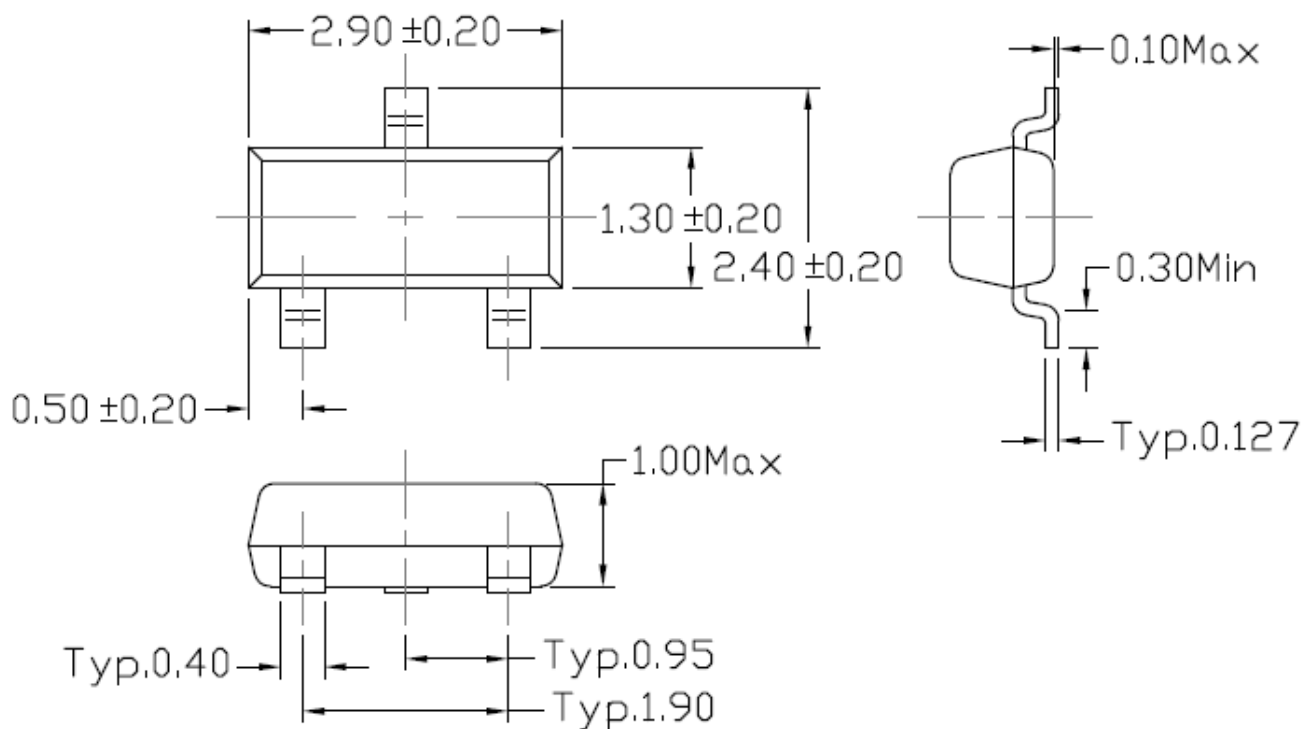


Figure 12: Switching Time Waveform



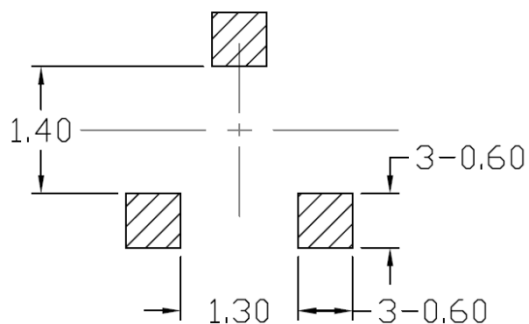


**Package Dimension** *Dimensions in mm unless otherwise stated*



Note: Dimensions in mm

**Recommended pad layout for surface mount leadform**



Note: Dimensions in mm



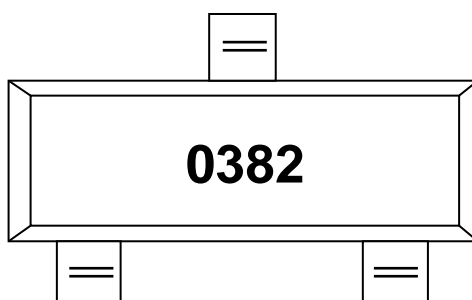


**CTL0382PS**

**P-Channel Enhancement MOSFET**

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## Marking Information



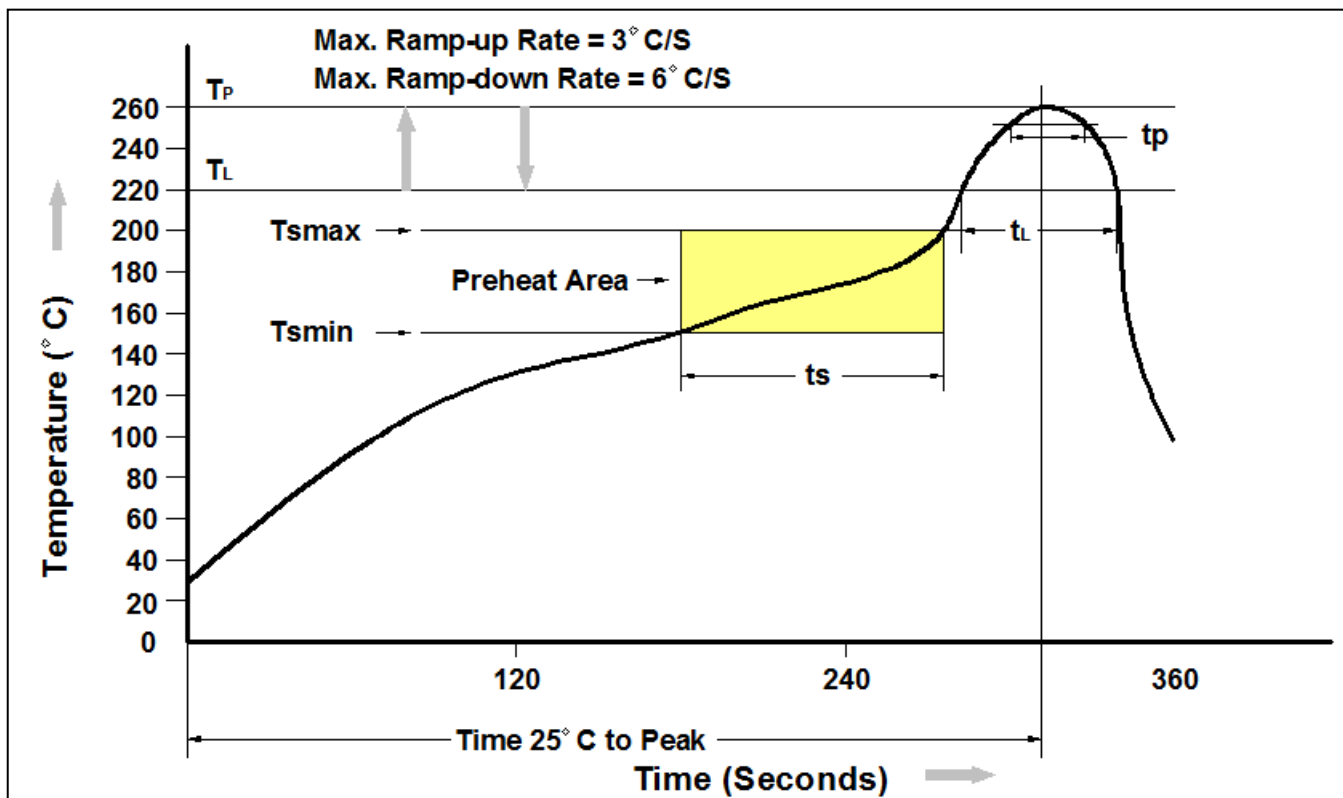
0382 : Device Number

## Ordering Information

<b>Part Number</b>	<b>Description</b>	<b>Quantity</b>
CTL0382PS	SOT-23 Reel	3000 pcs



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>min</sub> )	150°C
Temperature Max. (T <sub>max</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>min</sub> to T <sub>max</sub> )	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

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